

Electronic Patent Application Fee Transmittal

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|---|--|-----------------|---------------|-----------------------------|
| Application Number: | 10552540 | | | |
| Filing Date: | 11-Oct-2005 | | | |
| Title of Invention: | Thermosetting resin composition, multilayer body using same, and circuit board | | | |
| First Named Inventor/Applicant Name: | Shigeru Tanaka | | | |
| Filer: | Troy M. Schmelzer/Firoozeh Vakilzadeh | | | |
| Attorney Docket Number: | 81844.0044 | | | |
| Filed as Large Entity | | | | |
| U.S. National Stage under 35 USC 371 Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Independent claims in excess of 3 | 1614 | 3 | 200 | 600 |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 600 |